



#### 40V 175°C P-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>C</sub> = +25°C
-40V	$26m\Omega @ V_{GS} = -10V$	-50A

## **Description and Applications**

This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Motor Control
- Backlighting
- DC-DC Converters
- Printer Equipment

### **Features**

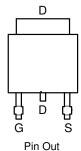
- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switch (UIS) Test in Production
- Low On-Resistance
- Fast Switching Speed
- Low Input/Output Leakage
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Datasheet (<u>DMPH4023SK3Q</u>)

#### **Mechanical Data**

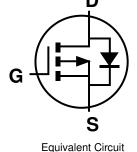
- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Finish Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.33 grams (Approximate)



Top View



Top View



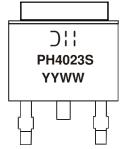
Ordering Information (Note 4)

Part Number	Case	Packaging
DMPH4023SK3-13	TO252 (DPAK)	2,500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**



J!! = Manufacturer's Marking
 PH4023S = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Last Two Digits of Year (ex: 17 = 2017)
 WW = Week Code (01 to 53)



# **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage		$V_{DSS}$	-40	V
Gate-Source Voltage		$V_{GSS}$	±20	V
Continuous Drain Current (Note 6) $V_{GS} = -10V$ $T_C = +25^{\circ}C$ $T_C = +100^{\circ}C$		ΙD	-50 -35	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	-70	Α	
Maximum Continuous Body Diode Forward Current (Note 6)		Is	-4	Α
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)		I <sub>SM</sub>	-70	Α
Avalanche Current, L = 0.1mH (Note 7)		I <sub>AS</sub>	-40	Α
Avalanche Energy, L = 0.1mH (Note 7)		Eas	85	mJ

## Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

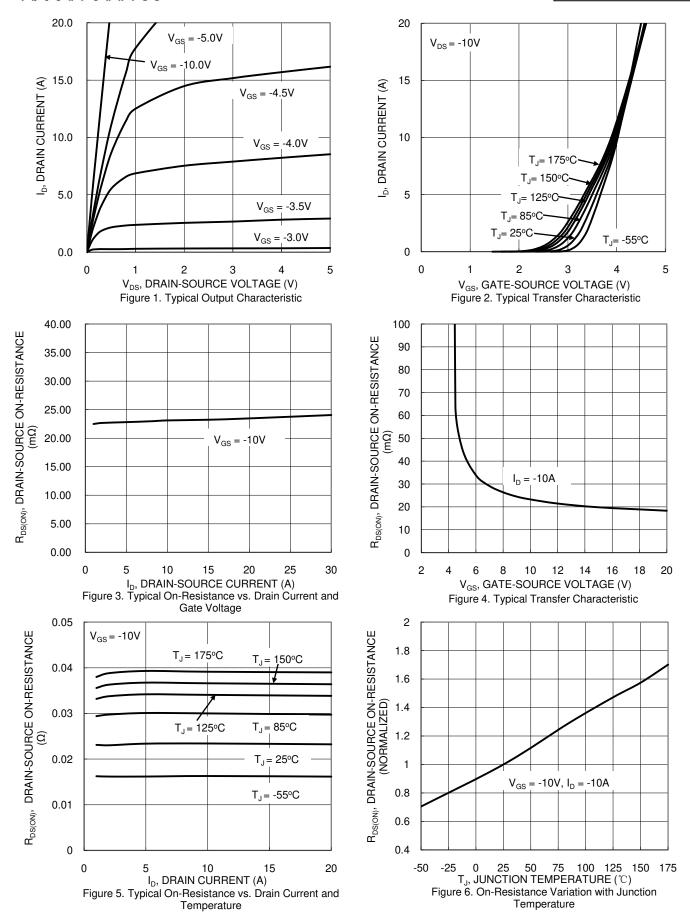
Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		$P_{D}$	2.1	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{ heta JA}$	71	°C/W
Total Power Dissipation (Note 6)		P <sub>D</sub>	3.6	W
Thermal Resistance, Junction to Ambient (Note 6)  Steady State		$R_{ heta JA}$	41	°C/W
Thermal Resistance, Junction to Case		$R_{\theta JC}$	1.5	3C/VV
Operating and Storage Temperature Range		T <sub>J,</sub> T <sub>STG</sub>	-55 to +175	°C

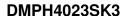
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-40			٧	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>			-1	μΑ	$V_{DS} = -40V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	$V_{GS(TH)}$	-1		-3	٧	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	21	26	mΩ	$V_{GS} = -10V, I_D = -10A$	
Diode Forward Voltage	$V_{SD}$	_	-0.75	-1.2	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C <sub>iss</sub>	_	1091	_	pF	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V, f = 1MHz	
Output Capacitance	Coss		288	_	рF		
Reverse Transfer Capacitance	Crss	_	111	_	pF		
Gate Resistance	$R_g$	_	14	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge	Qg	_	18.7	_	nC	$V_{DS} = -20V, I_{D} = -10A,$	
Gate-Source Charge	Qgs	_	4.2	_	nC	, , ,	
Gate-Drain Charge	$Q_{gd}$	_	5.0	_	nC	$V_{GS} = -10V$	
Turn-On Delay Time	t <sub>D(ON)</sub>	_	5.3	_	ns	$V_{DD} = -20V, V_{GS} = -10V,$ $R_{G} = 6\Omega, I_{D} = -10A$	
Turn-On Rise Time	t <sub>R</sub>	_	4.8	_	ns		
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	30.7	_	ns		
Turn-Off Fall Time	t <sub>F</sub>	_	23.4	_	ns		
Reverse Recovery Time	t <sub>RR</sub>	_	17.8	_	ns	I <sub>F</sub> = -10A, di/dt = -100A/μs	
Reverse Recovery Charge	Q <sub>RR</sub>	_	9.2	_	nC		

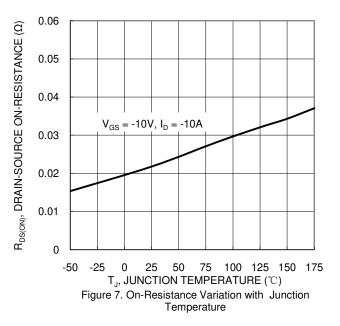
- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
   Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7.  $I_{AS}$  and  $E_{AS}$  ratings are based on low frequency and duty cycles to keep  $T_J$  = +25°C.
- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to product testing.

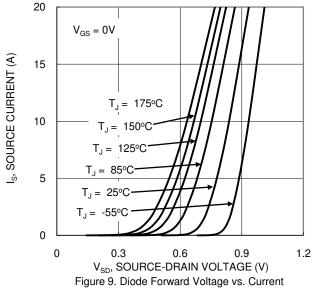


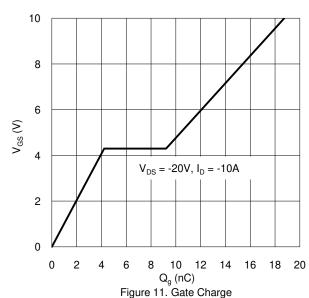


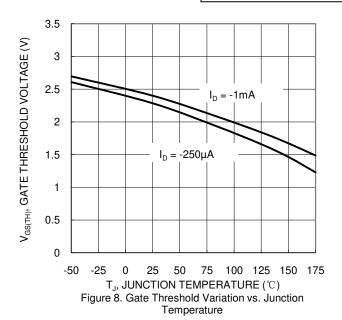


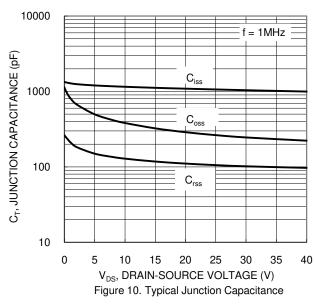


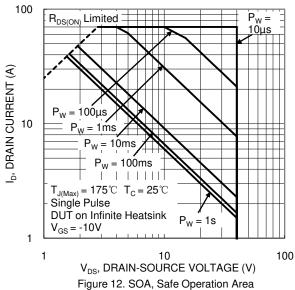














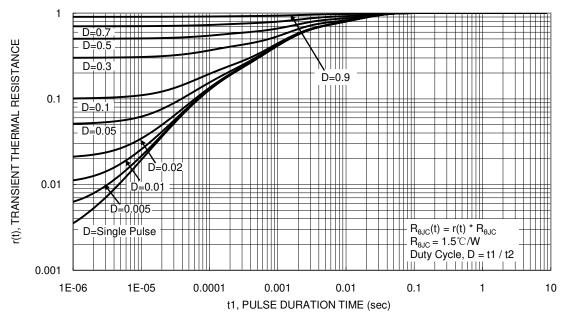


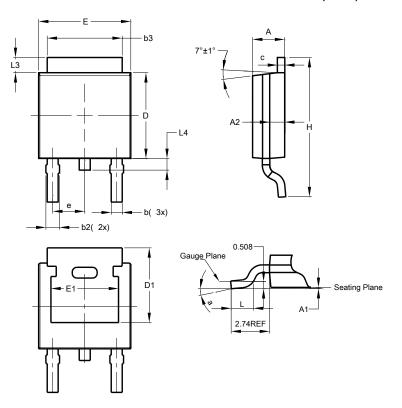
Figure 13. Transient Thermal Resistance



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### TO252 (DPAK)

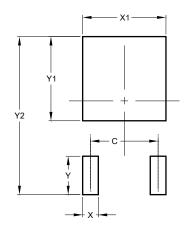


TO252 (DPAK)					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
<b>A</b> 1	0.00	0.13	0.08		
A2	0.97	1.17	1.07		
b	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b3	5.21	5.46	5.33		
С	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21	-	-		
e	-	-	2.286		
Е	6.45	6.70	6.58		
E1	4.32	-	-		
Н	9.40	10.41	9.91		
L	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
L4	0.64	1.02	0.83		
а	0°	10°	-		
All Dimensions in mm					

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### TO252 (DPAK)



Dimensions	Value (in mm)		
С	4.572		
Х	1.060		
X1	5.632		
Υ	2.600		
Y1	5.700		
Y2	10.700		



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